N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- ☑ Surface-mounted package
- ☑ Advanced trench cell design
- ☑ Extremely low threshold voltage

1.2 Applications

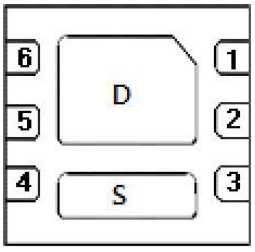
- ☑ Portable appliances
- ☑ Battery management

1.3 Quick reference

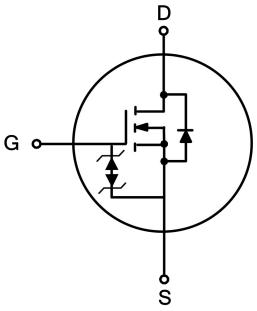
- ☑ BV ≧ 30 V
- ☑ P_{tot} ≦ 1.56 W
- ☑ I_D ≦ 6.8 A
- ☑ $R_{DS(ON)}$ ≦ 22 mΩ @ V_{GS} = 4.5 V
  $R_{DS(ON)}$ ≦ 28 mΩ @ V_{GS} = 2.5 V
  $R_{DS(ON)}$ ≦ 36 mΩ @ V_{GS} = 1.8 V

2. Pin Description

Pin	Description
1,2,5,6	Drain
3	Gate
4	Source



Bottom View
DFN2X2-6L



3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	T_A = 25 ℃	30	-	V
V_{GS}	Gate-Source Voltage	T_A = 25 ℃	-	± 10	V
I_D*	Drain Current	T_A = 25 ℃, V_{GS} = 4.5 V	-	6.8	A
I_{DM}*,**	Pulsed Drain Current	T_A = 25 ℃, V_{GS} = 4.5 V	-	27.2	A
P_{tot}*	Total Power Dissipation	T_A = 25 ℃	-	1.56	W
T_{stg}	Storage Temperature		- 55	150	℃
T_J	Junction Temperature		-	150	℃
I_S*	Diode Forward Current	T_A = 25 ℃	-	6.8	A
$R_{\theta JA}$*	Thermal Resistance- Junction to Ambient		-	80	℃ / W

Notes：

* Surface Mounted on 1 in^2 pad area, t ≤ 10 sec

** Pulse width ≤ 300 μs, duty cycle ≤ 2 %

*** Limited by bonding wire

4. Marking Information

Product Name	Marking
KJ4800N2	4800 YWWXXX YWW: Date Code

5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ4800N2	DFN2*2				

Note: KUAIJIEXIN defines " Green " as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC / JEDEC J-STD-020C)

6. Electrical Characteristics (T_A = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_{DS} = 250 μA	30	–	–	V
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_{DS} = 250 μA	0.5	–	1.0	V
I_{DSS}	Drain Leakage Current	V_{DS} = 24 V, V_{GS} = 0 V	-	-	1	μA
		T_J = 85 ℃	-	-	30	μA
I_{GSS}	Gate Leakage Current	V_{GS} = ± 10 V, V_{DS} = 0 V	-	-	± 20	uA
$R_{DS(ON)}$[a]	On-State Resistance	V_{GS} = 4.5 V, I_{DS} = 6 A	-	18	22	mΩ
		V_{GS} = 2.5 V, I_{DS} = 4 A	-	22	28	
		V_{GS} = 1.8 V, I_{DS} = 3 A	-	28	36	
Diode Characteristics						
V_{SD}[a]	Diode Forward Voltage	I_{SD} = 6 A, V_{GS} = 0 V	-	-	1.2	V
t_{rr}	Reverse Recovery Time	I_{SD} = 6 A, dI_{SD} / dt = 100 A / μs	-	8.9	-	nS
Q_{rr}	Reverse Recovery Charge		-	2.8	-	nC
Dynamic Characteristics[b]						
C_{iss}	Input Capacitance	V_{GS} = 0 V, V_{DS} = 15 V Frequency = 1 MHz	-	1052	-	pF
C_{oss}	Output Capacitance		-	70	-	
C_{rss}	Reverse Transfer Capacitance		-	60	-	
t_d(on)	Turn-on Delay Time	V_{DS} = 15 V, V_{GEN} = 4.5 V, R_G = 4.5 Ω, R_L = 2.5 Ω, I_{DS} = 6 A	-	6	-	uS
t_r	Turn-on Rise Time		-	30	-	
t_d(off)	Turn-off Delay Time		-	33	-	
t_f	Turn-off Fall Time		-	25	-	
Gate Charge Characteristics[b]						
Q_g	Total Gate Charge	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{DS} = 6 A	-	11.8	-	nC
Q_{gs}	Gate-Source Charge		-	3	-	
Q_{gd}	Gate-Drain Charge		-	3	-	

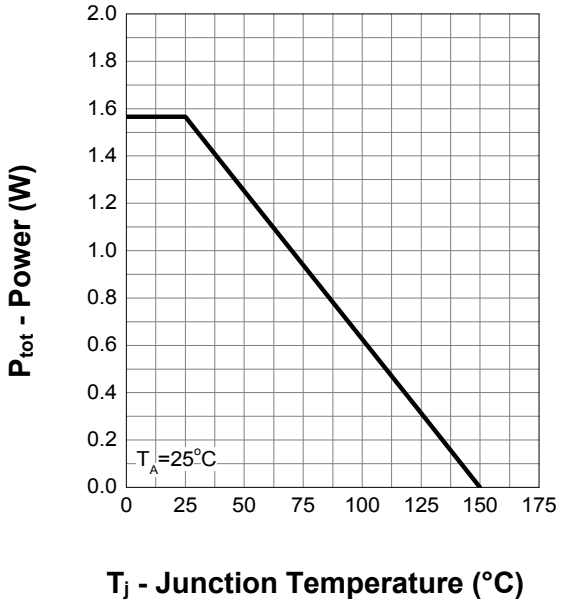
Notes：

a : Pulse test ; pulse width ≤ 300 μs, duty cycle ≤ 2 %

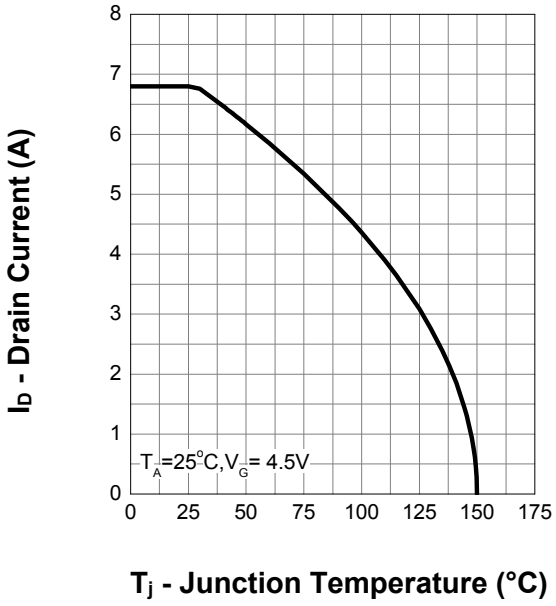
b : Guaranteed by design, not subject to production testing

7. Typical Characteristics

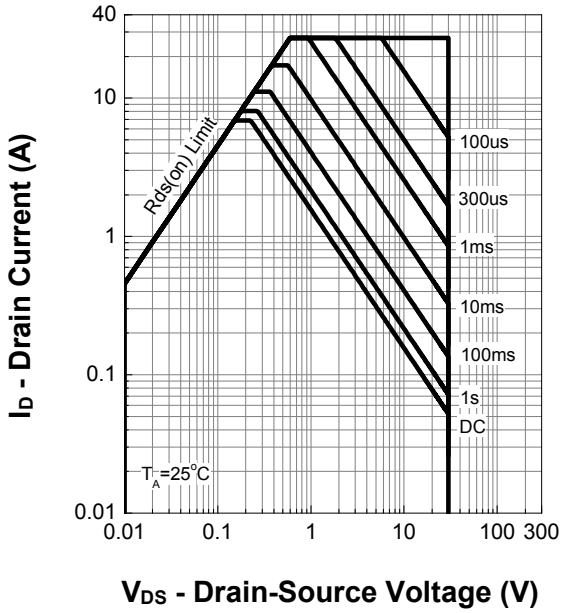
Power Capability



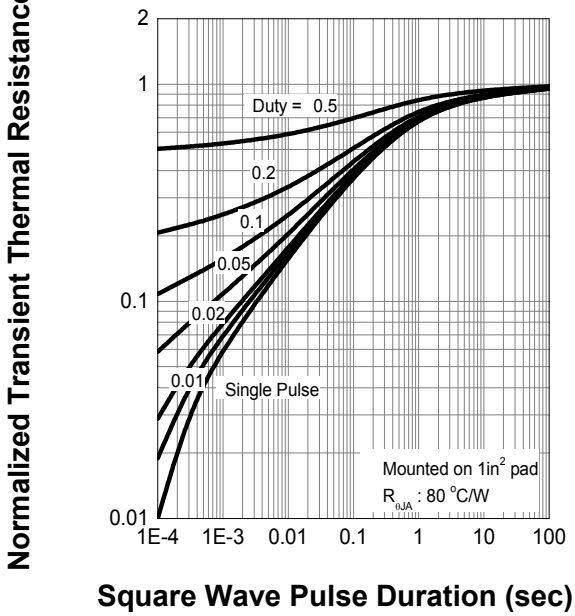
Current Capability



Safe Operation Area

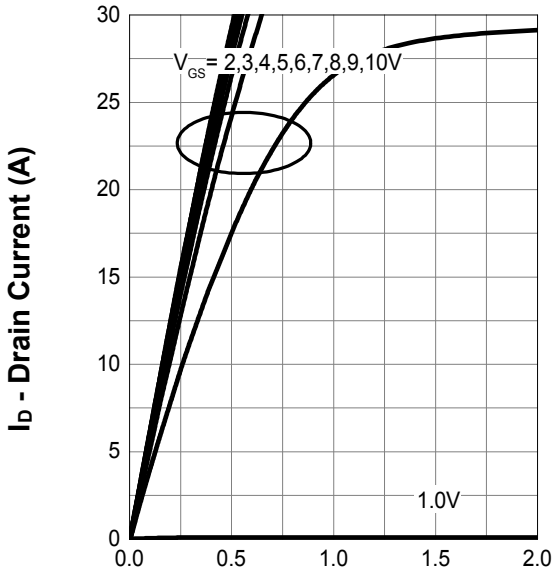


Transient Thermal Impedance

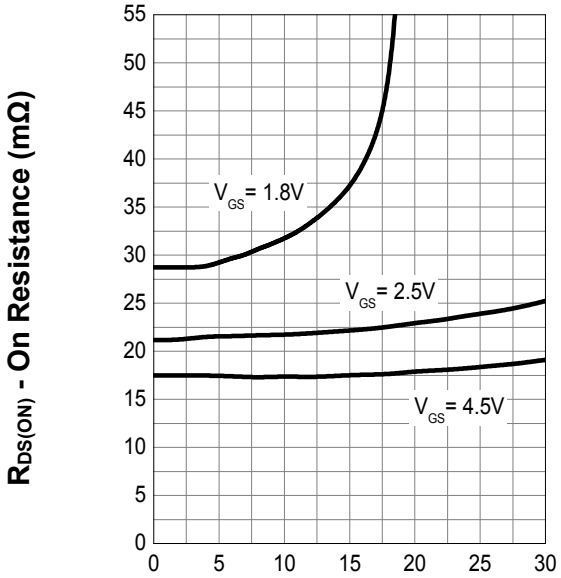


7. Typical Characteristics (cont.)

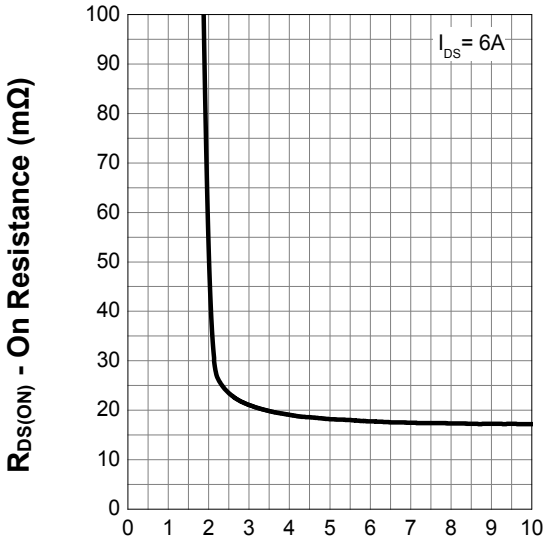
Output Characteristics



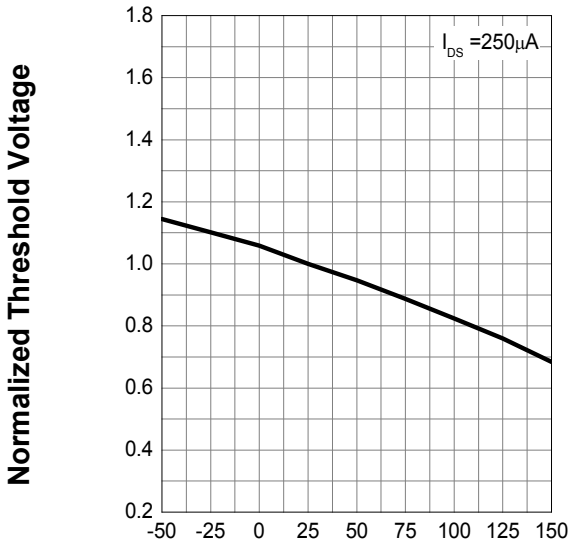
On Resistance



Transfer Characteristics

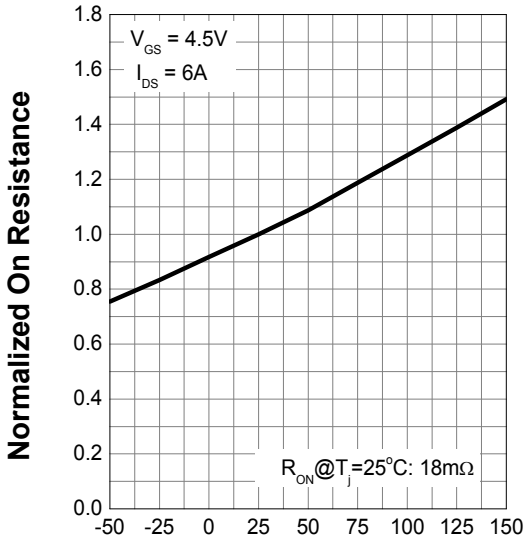


Normalized Threshold Voltage

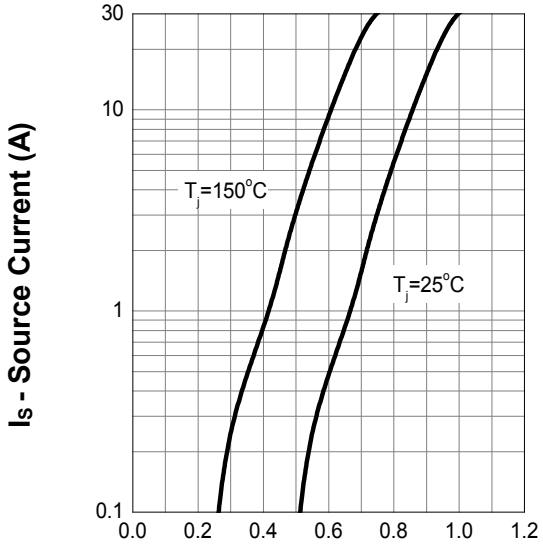


7. Typical Characteristics (cont.)

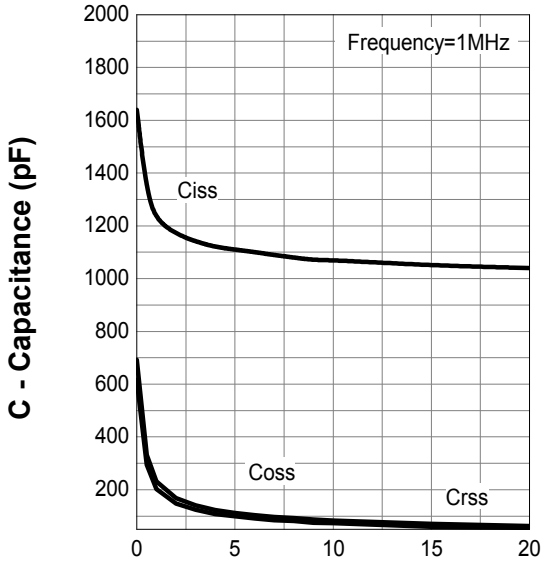
Normalized On Resistance



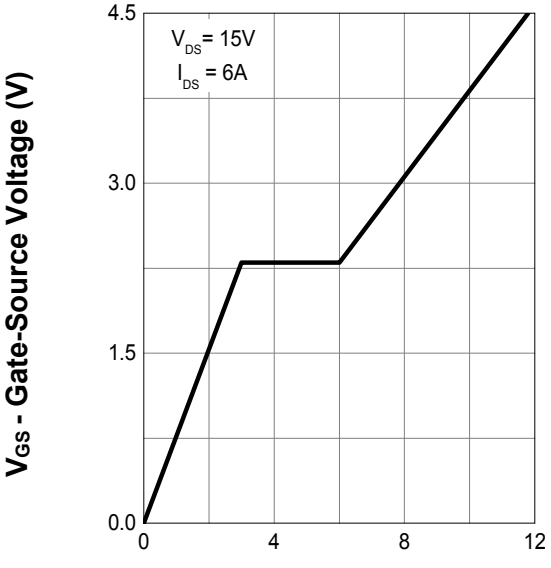
Diode Forward Current



Capacitance

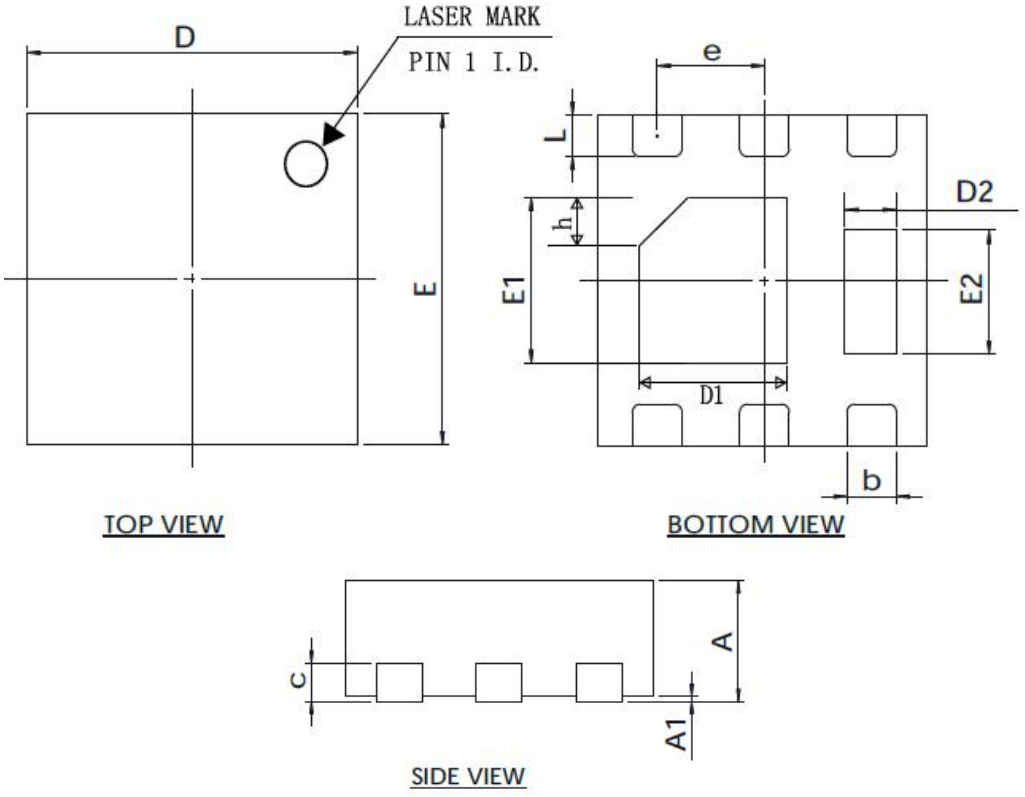


Gate Charge



8.Package Dimensions

DFN2*2-6L



Symbol	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	NA	0.02	0.05
b	0.20	0.27	0.34
c	0.18	0.20	0.25
D	1.95	2.00	2.07
E	1.95	2.00	2.07
D1	0.80	0.90	1.00
E1	0.90	1.00	1.10
D2	0.20	0.30	0.40
E2	0.65	0.75	0.85
L	0.20	0.25	0.35
h	0.20	0.25	0.30
e	0.65BSC		